

### 3.2x1.0 x1.5mm Red & Yellow Chip LED

#### **OSRY1204C1E**

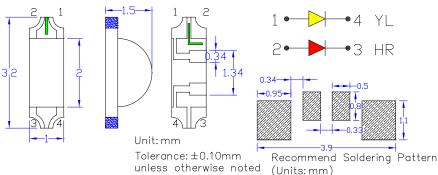
#### **■**Features

- Bi-color
- Super high brightness of surface mount LED
- Compact package outline (L x W x T) of 3.2mm x 1.0mm x1.5mm
- Compatible to IR reflow soldering.
- Water clear flat mold

#### **■**Applications

- Backlighting (switches, keys, etc.)
- Marker lights (e.g. steps, exit ways, etc.)

#### **■Outline Dimension**

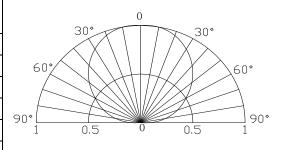


unless otherwise noted

# ■Absolute Maximum Rating

T4	C- 1 1	Val	11.4		
Item	Symbol	Red	Yellow	Unit	
DC Forward Current	$I_F$	20	20	mA	
Pulse Forward Current#	$I_{\mathrm{FP}}$	100	100	mA	
Reverse Voltage	$V_R$	5	5	V	
Power Dissipation	$P_{\mathrm{D}}$	46	46	mW	
Operating Temperature	Topr	-40 ~ +85			
Storage Temperature	Tstg	-40∼ +85			
Lead Soldering Temperature	Tsol	260°C/10sec			

## Directivity



#Pulse width Max 0.1ms, Duty ratio max 1/10

## **■Electrical -Optical Characteristics**

	Number Color		V <sub>F</sub> (V)		I <sub>R</sub> (µA)	Iv(mcd)		λD(nm)			2θ1/2(deg)			
Part Number			Min.	Тур.	Max.	Max.	Min.	Тур.	Max.	Min.	Тур.	Max.	Тур.	
				I <sub>F</sub> =5mA			V <sub>R</sub> =5V	I <sub>F</sub> =5mA						
OSRY1204C1E	Red	HR	•	-	1.7	2.3	10	-	30	-	620	625	630	120
	Vellow	VI	_	_	17	2.3	10	_	30	_	585	590	595	120

 $(Ta=25^{\circ}C)$ 

(Ta=25°C)

## **LED & Application Technologies**









<sup>\*1</sup> Tolerance of measurements of dominant wavelength is  $\pm 1$ nm

<sup>\*2</sup> Tolerance of measurements of luminous intensity is ±15%

<sup>\*3</sup> Tolerance of measurements of forward voltage is +0.1V



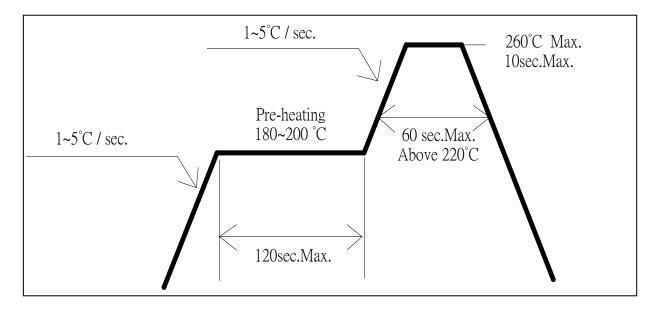
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### **■** Soldering Conditions

	Reflow Soldering	Hand Soldering			
Pre-Heat	180 ~ 200°C				
Pre-Heat Time	120 sec. Max.				
Peak Temperature	260°C Max.	Temperature	350°C Max.		
Dipping Time	10 sec. Max.	Soldering time	3 sec. Max.		
Condition	Refer to Temperature-profile		(one time only)		

#### • Reflow Soldering Condition(Lead-free Solder)



- \*Recommended soldering conditions vary according to the type of LED
- \*Although the recommended soldering conditions are specified in the above table, reflow, or hand soldering at the lowest possible temperature is desirable for the LEDs.
- \*A rapid-rate process is not recommended for cooling the LEDs down from the peak temperature.
- •All SMD LED products are pb-free soldering available.
- Occasionally there is a brightness decrease caused by the influence of heat or ambient atmosphere during air reflow. It is recommended that the User use the nitrogen reflow method.
- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than two times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board.







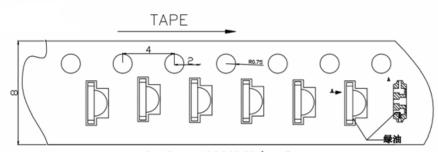




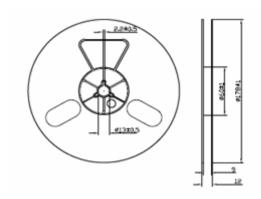
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# **■**Packaging

# 1. Reel & Tape Dimensions (3000PCS/Reel)

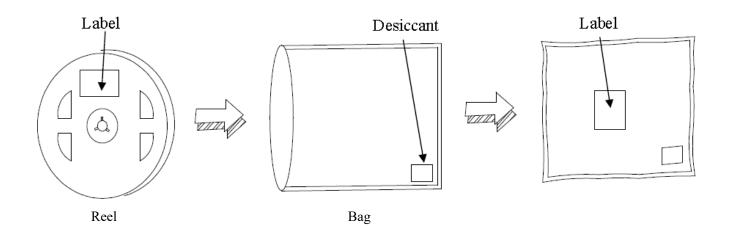


Package:3000PCS/reel



Notes: All dimensions are in millimeters

# 2. Bag Packaging











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#### **■** Cautions:

- 1. After open the package, the LED´s floor life is 4 Weeks under 30℃ or less and 60%RH or less(MSL:2a).
- 2. Heat generation must be taken into design consideration when using the LED.
- 3. Power must be applied resistors for protection, over current would be caused the optic damage to the devices and wavelength shift.
- 4. Manual tip solder may cause the damage to Chip devices, so advised that heat of iron should be lower than 15W with temperature control under 5 seconds at 230-260 deg. C. (The device would be got damage in re working process, recommended under 5 seconds at 230-260 deg. C)
- 5. All equipment and machinery must be properly grounded. It is recommended to use a wristband or anti-electrostatic glove when handing the LED.
- 6. Use IPA as a solvent for cleaning the LED. The other solvent may dissolve the LED package and the epoxy, Ultrasonic cleaning should not be done.
- 7. Damaged LED will show unusual characteristics such as leak current remarkably increase, turn-on voltage becomes lower and the LED get unlight at low current.

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